



VMDSEMI

**VUTL004R062NA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
40V	6.2mΩ@10V	70A
	8.5mΩ@4.5V	

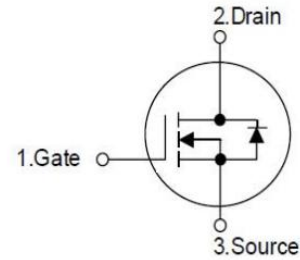
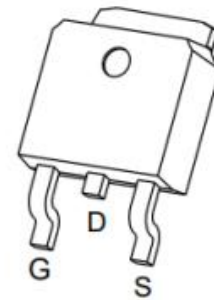


Figure 1 Symbol of VUTL004R062NA

## Features

- Trench Technology Power MOSFET
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

## Package Type



## TO-252-2L

Figure 2 Package Type of VUTL004R062NA

## Application

- Battery protection applications
- Power Switch Application

## Ordering Information

Product Name	Package
VUTL004R062NA	TO-252-2L

**Absolute Maximum Ratings** ( $T_A = 25\text{ °C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	70	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	280	
Avalanche Current <sup>Note3</sup>	$I_{AS}$	29	A
Single Pulsed Avalanche Energy <sup>Note3</sup>	$E_{AS}$	210	mJ
Total Power Dissipation <sup>Note5</sup>	$P_D$	125	W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note6</sup>	$R_{\theta JA}$		47		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		1		°C/W

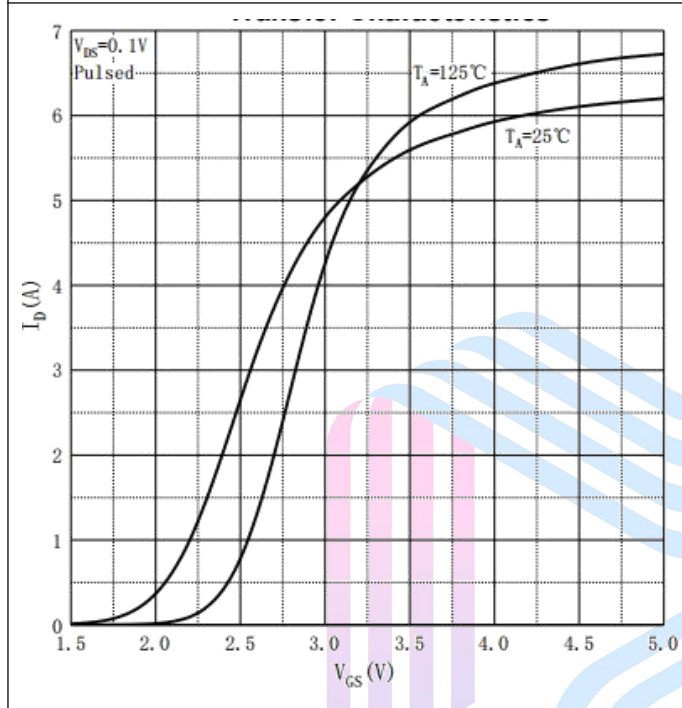
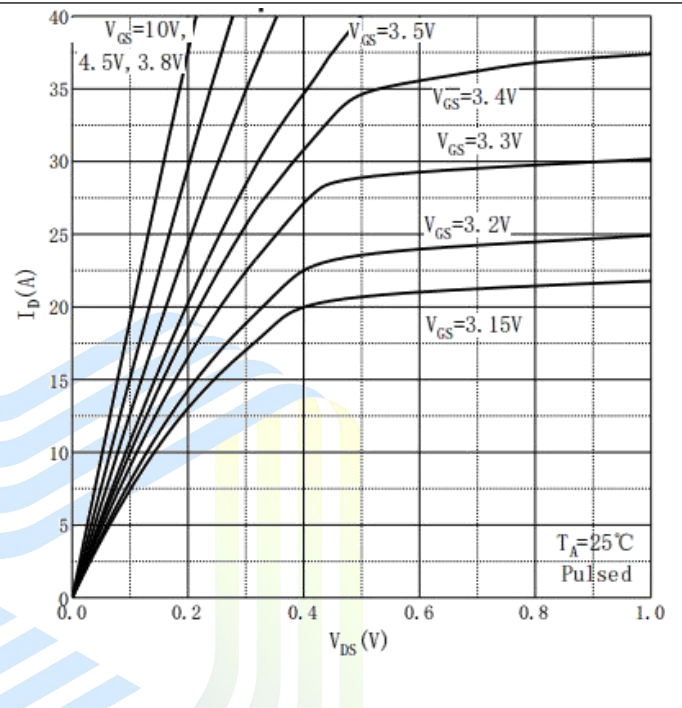
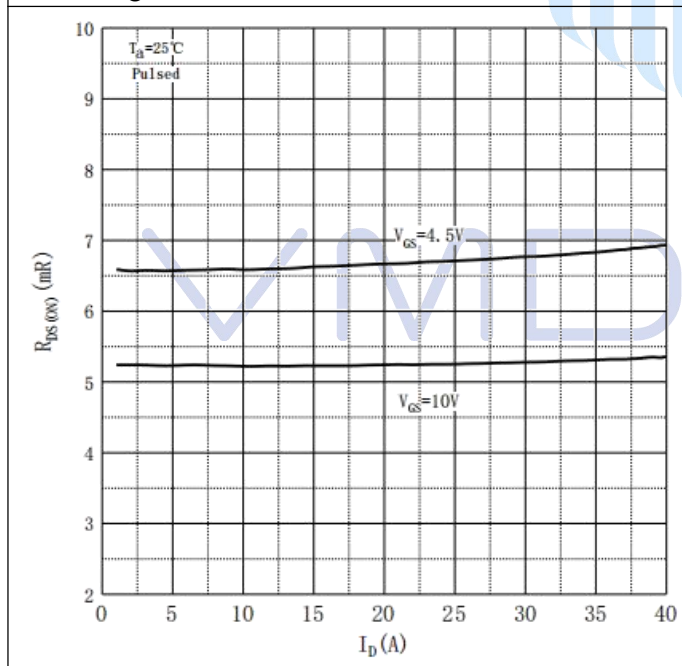
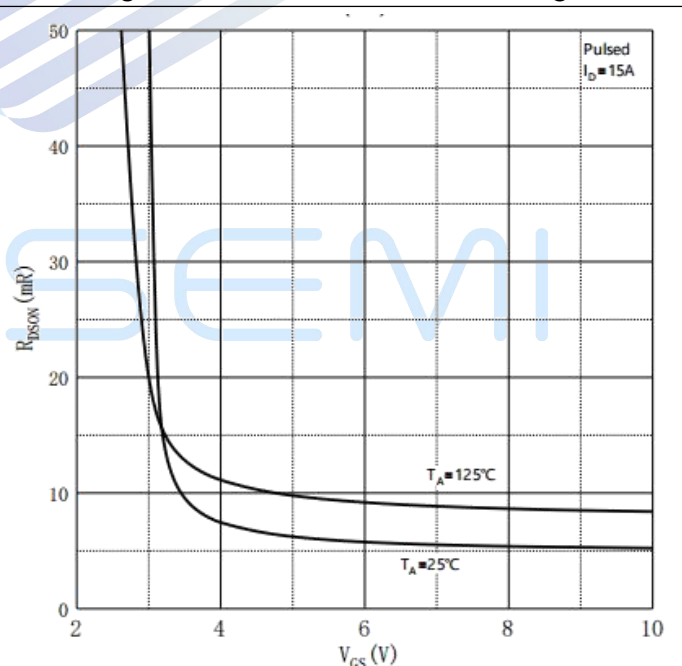
**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

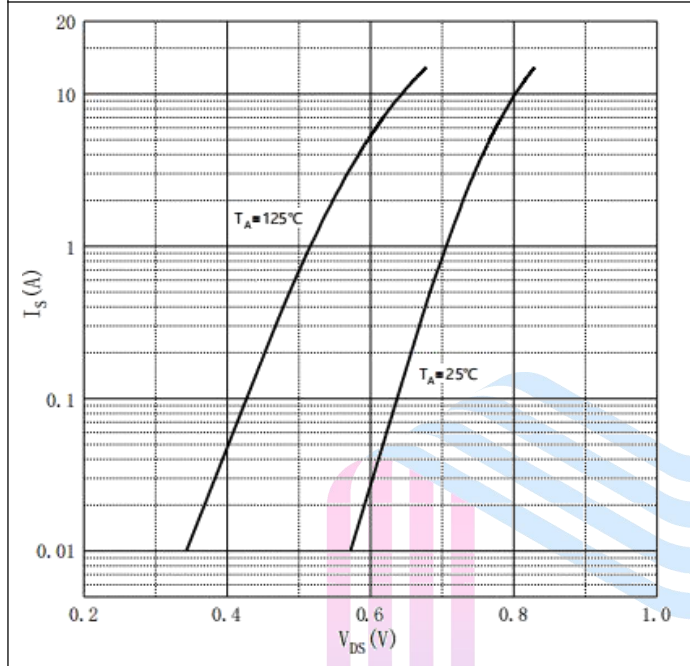
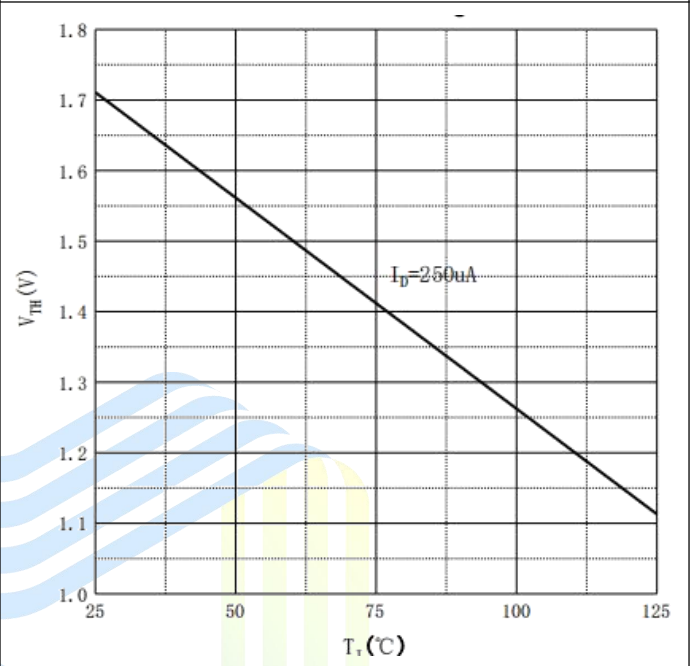
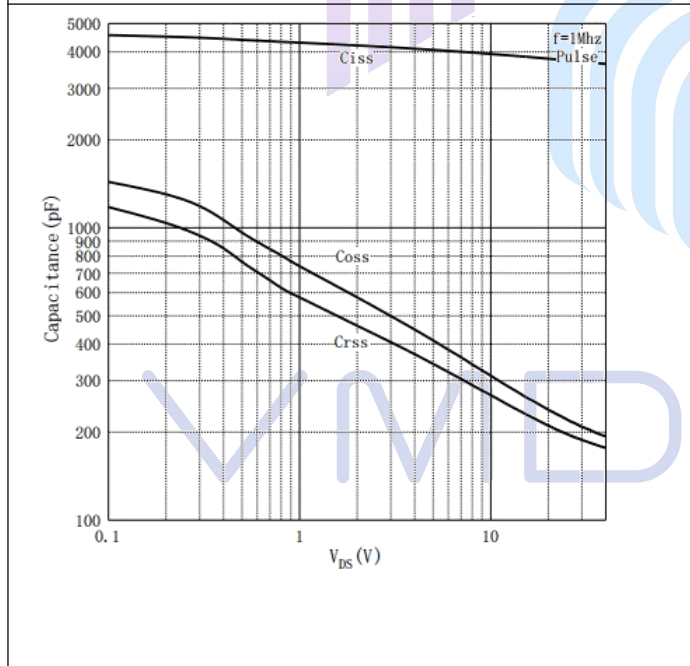
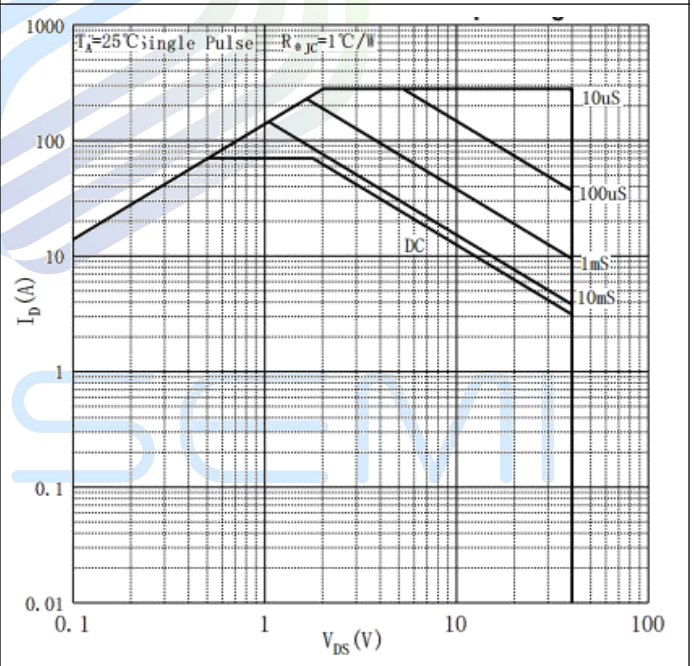
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	40			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=40V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note4</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.7	3.0	V
Static Drain-Source On-Resistance <sup>Note4</sup>	$R_{DS(on)}$	$V_{GS}=10V, I_D=15A$		4.8	6.2	mΩ
		$V_{GS}=4.5V, I_D=10A$		5.6	8.5	
Forward Transconductance <sup>Note4</sup>	$g_{FS}$	$V_{DS}=5V, I_D=20A$		78		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=20V$		3747		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		237		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		210		pF
Total Gate Charge	$Q_g$	$V_{DS}=20V$		67		nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=10V$		12		
Gate-Drain Charge	$Q_{gd}$	$I_D=15A$		9		
Gate Resistance	$R_g$	$f=1MHz, \text{Open drain}$		1.88		Ω
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=20V$		11		ns
Turn-on Rise Time	$t_r$	$V_{GS}=10V$		10		
Turn-off Delay Time	$t_{d(off)}$	$R_L=1\Omega$		38		
Turn-off Fall Time	$t_f$	$R_G=3\Omega$		11		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note4</sup>	$V_{SD}$	$V_{GS}=0V, I_S=15A$			1.2	V

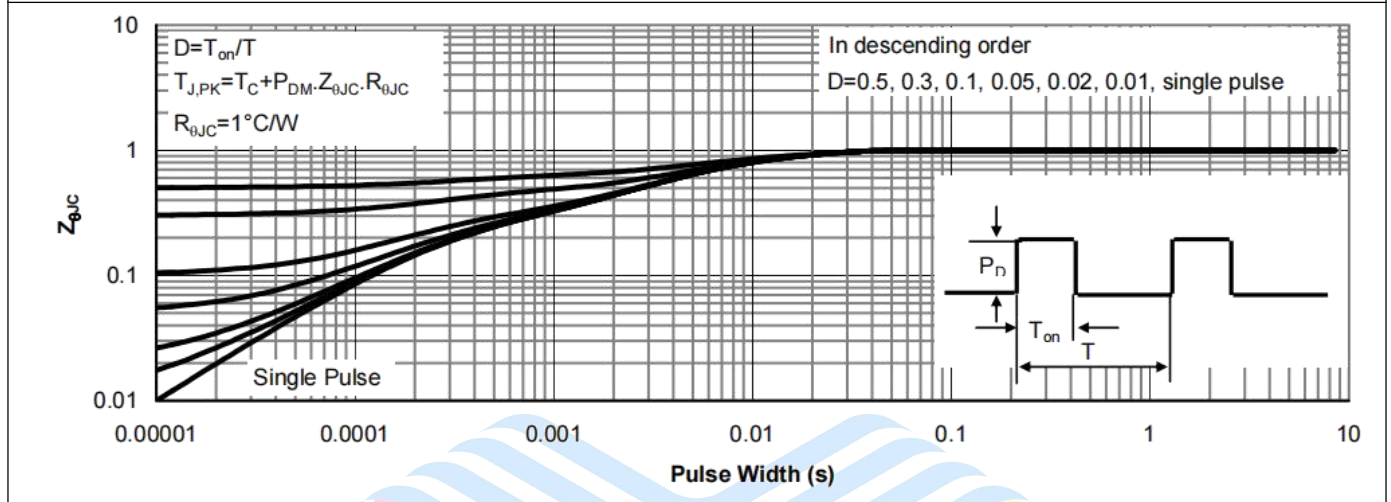
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.EAS condition:  $V_{DD} = 20V, V_{GS} = 10V, L = 0.5mH, R_G=25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
- 4.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 6.Device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

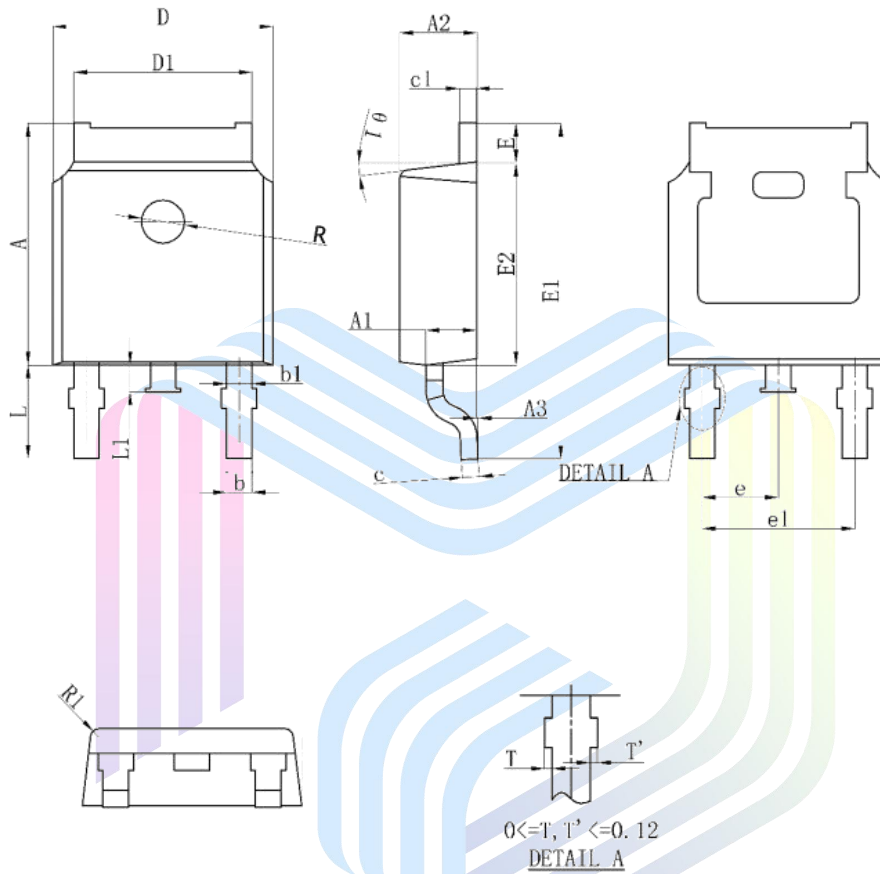
## Typical Performance Characteristics

**Figure 3: Transfer Characteristics**

**Figure 4: Output Characteristics**

**Figure 5: On-Resistance vs. Drain Current**

**Figure 6: On-Resistance vs. Gate Voltage**


**Figure 7: Body Diode Characteristics**

**Figure 8: Threshold Voltage**

**Figure 9: Typical Capacitance**

**Figure 10: Safe Operation Area**


**Figure 11: Normalized Maximum Transient Thermal Impedance**



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**Mechanical Dimensions:**
**TO-252-2L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	7.050	7.150	0.278	0.281
A1	0.960	1.060	0.038	0.042
A2	2.200	2.400	0.087	0.094
A3	0.000	0.100	0.000	0.004
b	0.760REF		0.030REF	
b1	1.000REF		0.039REF	
c	0.508REF		0.020REF	
c1	0.508REF		0.020REF	
D	6.550	6.650	0.258	0.262
D1	5.100	5.460	0.201	0.215
E	0.950	1.050	0.037	0.041
E1	9.700	10.400	0.382	0.409
E2	6.000	6.200	0.236	0.244
e	2.286BSC		0.090BSC	
e1	4.572REF		0.180REF	
L	2.650	2.950	0.104	0.116
L1	0.700	0.900	0.028	0.035
θ1	7°REF		7°REF	
R	1.300REF		0.051REF	
R1	0.250REF		0.010REF	



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